

NEC

NEC Electronics Inc.

μPD43254B
65,536 x 4-Bit
Static CMOS RAM

Description

The μPD43254B is a 65,536-word by 4-bit static RAM fabricated with advanced silicon-gate technology. CMOS peripheral circuits and N-channel memory cells with polysilicon resistors make the μPD43254B a high-speed device that requires very low power and no clock or refreshing.

The μPD43254B is available in standard 24-pin plastic DIP and SOJ packaging.

Features

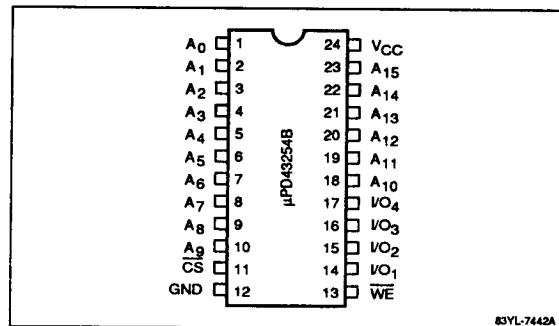
- 65,536-word x 4-bit organization
- Single +5-volt power supply
- Fully static operation—no clock or refreshing
- TTL-compatible inputs and outputs
- Common I/O capability
- Low power dissipation
 - 140 mA max (active)
 - 2 mA max (standby)
- Standard 24-pin plastic DIP and SOJ packaging

Ordering Information

Part Number	Access Time (max)	Package
μPD43254BCR-15	15 ns	24-pin plastic DIP
	CR-20	20 ns
	CR-25	25 ns
μPD43254BLA-15	15 ns	24-pin plastic SOJ
	LA-20	20 ns
	LA-25	25 ns

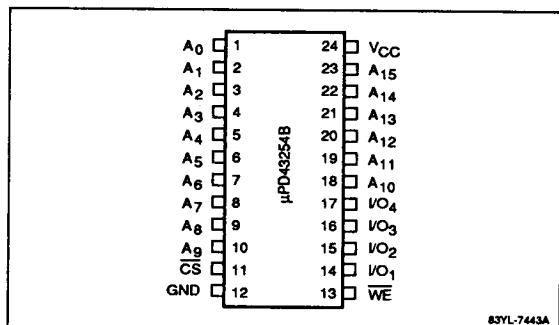
Pin Configurations

24-Pin Plastic DIP



83YL-7442A

24-Pin Plastic SOJ



83YL-7443A

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Pin Identification

Symbol	Function
A ₀ - A ₁₅	Address inputs
V _{O1} - V _{O4}	Data inputs and outputs
CS	Chip select
WE	Write enable
GND	Ground
V _{CC}	+5-volt power supply

Absolute Maximum Ratings

Supply voltage, V_{CC}	-0.5 to +7.0 V
Input and output voltages, V_{IN} (Note 1)	-0.5 to $V_{CC} + 0.3$ V
Operating temperature, T_{OPR}	0 to +70°C
Storage temperature, T_{STG}	-55 to +125°C
Power dissipation, P_D	1.0 W

Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

Notes:

(1) V_{IN} (min) = -3.0 V for 10 ns pulse.

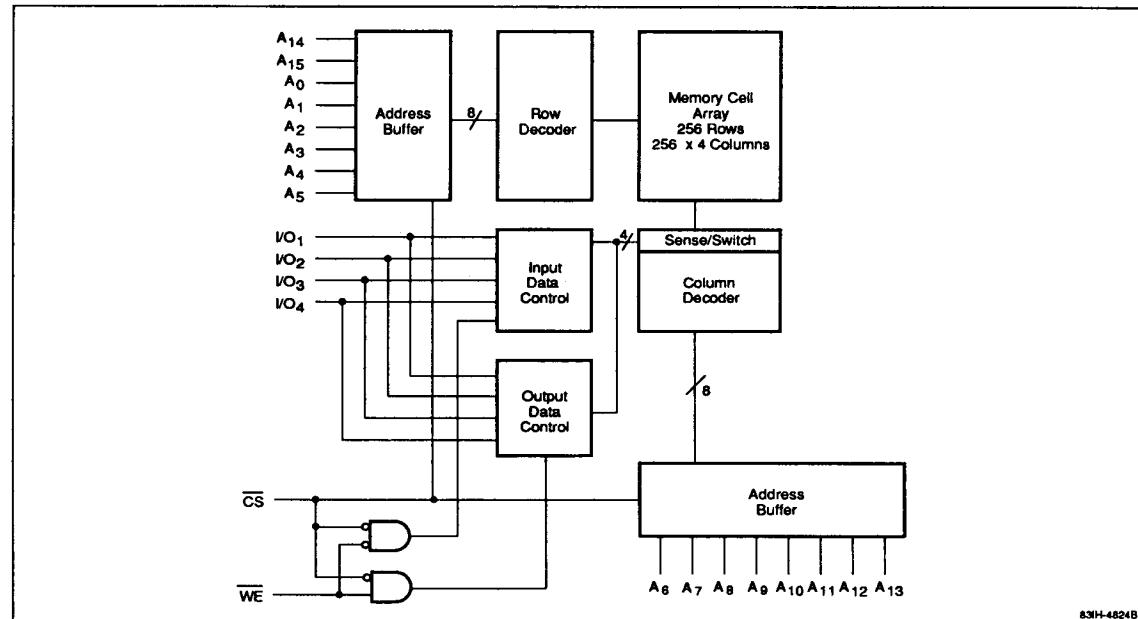
Capacitance

$T_A = 25^\circ\text{C}$; V_{IN} and $V_{DOUT} = 0$ V; $f = 1$ MHz (Note 1)

Parameter	Symbol	Min	Max	Unit
Input capacitance	C_{IN}	6	pF	
Output capacitance	C_{DOUT}	8	pF	

Notes:

(1) This parameter is sampled and not 100% tested.

Block Diagram

83H-4824B

DC Characteristics $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +5.0 \text{ V} \pm 10\%$

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Input leakage current	I_{IL}	-2		2	μA	$V_{IN} = 0 \text{ V to } V_{CC}$
Output leakage current	I_{LO}	-2		2	μA	$V_{OUT} = 0 \text{ V to } V_{CC}; \bar{CS} = V_{IH}$
Standby supply current	I_{SB}		30	mA		$\bar{CS} = V_{IH}$
	I_{SB1}		2	mA		$\bar{CS} \geq V_{CC} - 0.2 \text{ V}; V_{IN} \leq 0.2 \text{ V or } \geq V_{CC} - 0.2 \text{ V}$
Output voltage, low	V_{OL}		0.4	V		$I_{OL} = 8.0 \text{ mA}$
Output voltage, high	V_{OH}	2.4		V		$I_{OH} = -4.0 \text{ mA}$

AC Characteristics $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +5.0 \text{ V} \pm 10\%$

Parameter	Symbol	μPD43254B-15		μPD43254B-20		μPD43254B-25		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
Read Operation									
Operating supply current	I_{CC}		140		120		120	mA	$\bar{CS} = V_{IL}; I_{DOUT} = 0 \text{ mA}$
Read cycle time	t_{RC}	15		20		25		ns	(Note 2)
Address access time	t_{AA}		15		20		25	ns	
Chip select access time	t_{ACS}		15		20		25	ns	
Output hold from address change	t_{OH}	3		3		3		ns	
Chip selection to output in low-Z	t_{CLZ}	3		3		3		ns	(Note 3)
Chip deselection to output in high-Z	t_{CHZ}	0	6	0	8	0	10	ns	(Note 4)
Write Operation									
Write cycle time	t_{WC}	15		20		25		ns	(Note 2)
Chip select to end of write	t_{CW}	13		15		20		ns	
Address valid to end of write	t_{AW}	13		15		20		ns	
Address setup time	t_{AS}	0		0		0		ns	
Write pulse width	t_{WP}	12		14		18		ns	
Write recovery time	t_{WR}	0		0		0		ns	
Data valid to end of write	t_{DW}	10		12		14		ns	
Data hold time	t_{DH}	0		0		0		ns	
Write enable to output in high-Z	t_{WHZ}	0	6	0	8	0	10	ns	(Note 4)
Output active from end of write	t_{OW}	0		0		0		ns	(Note 3)

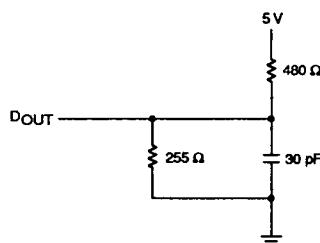
Notes:

- (1) Input pulse levels = GND to 3.0 V; input pulse rise and fall times = 3 ns; timing reference levels = 1.5 V; see figures 1 and 2 for output load.
- (2) All read cycle timings are referenced from the last valid address to the first transitioning address.

(3) Transition is measured at $\pm 200 \text{ mV}$ from steady-state voltage with the load shown in figure 2.

(4) Transition is measured at $V_{OL} + 200 \text{ mV}$ and $V_{OH} - 200 \text{ mV}$ with the load shown in figure 2.

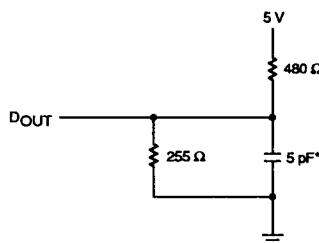
Figure 1. Output Load



*Including Scope and Jig

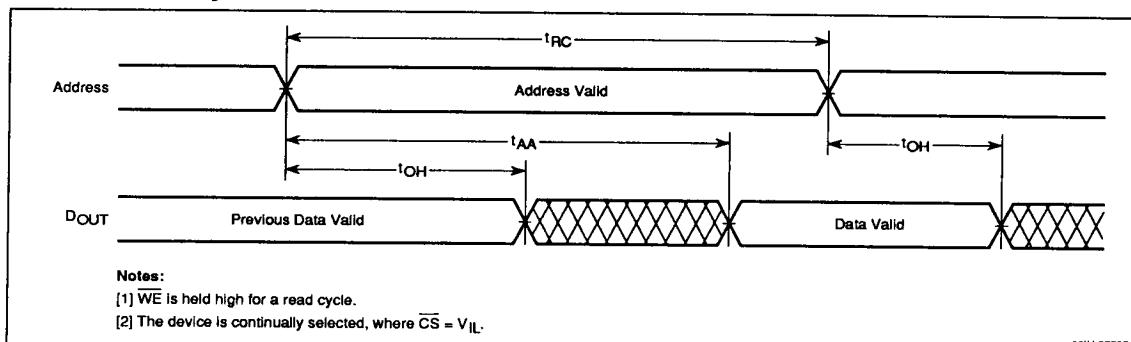
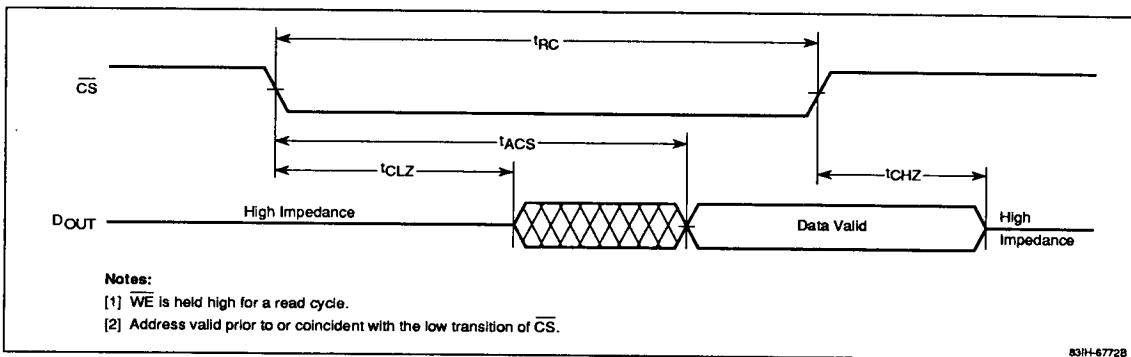
83H-4832A

Figure 2. Output Load for t_{CHZ} , t_{CLZ} , t_{WHz} , and t_{OW}



*Including Scope and Jig

83H-4831A

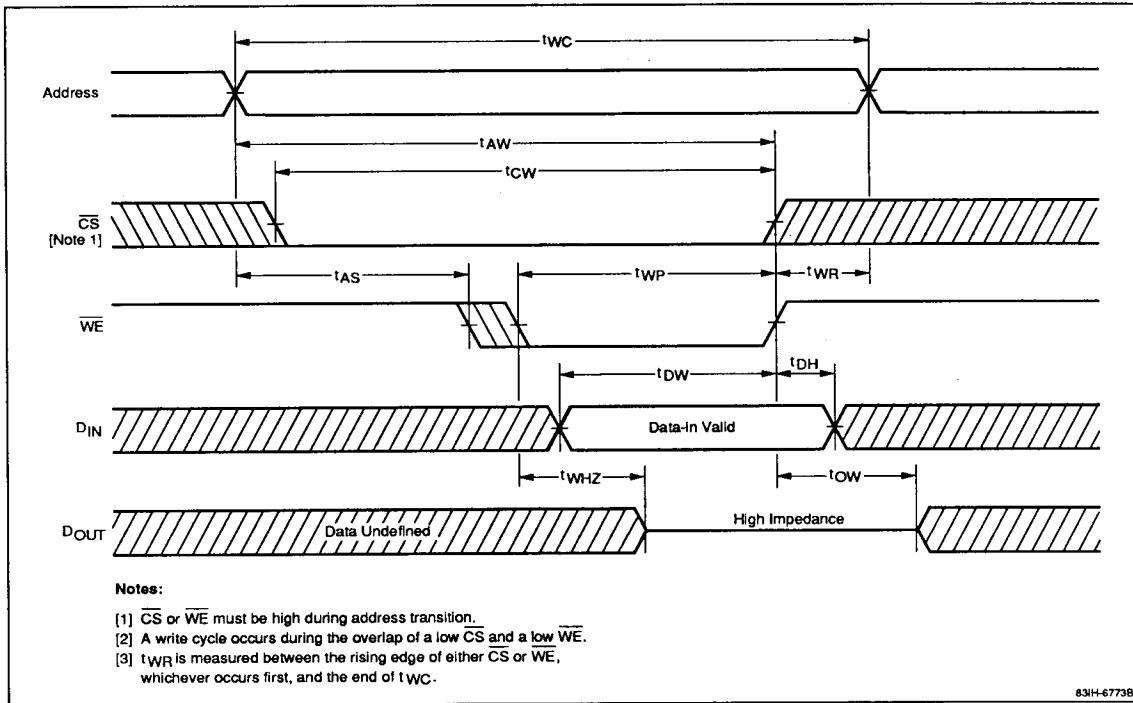
Timing Waveforms**Address Access Cycle****Chip Select Access Cycle**

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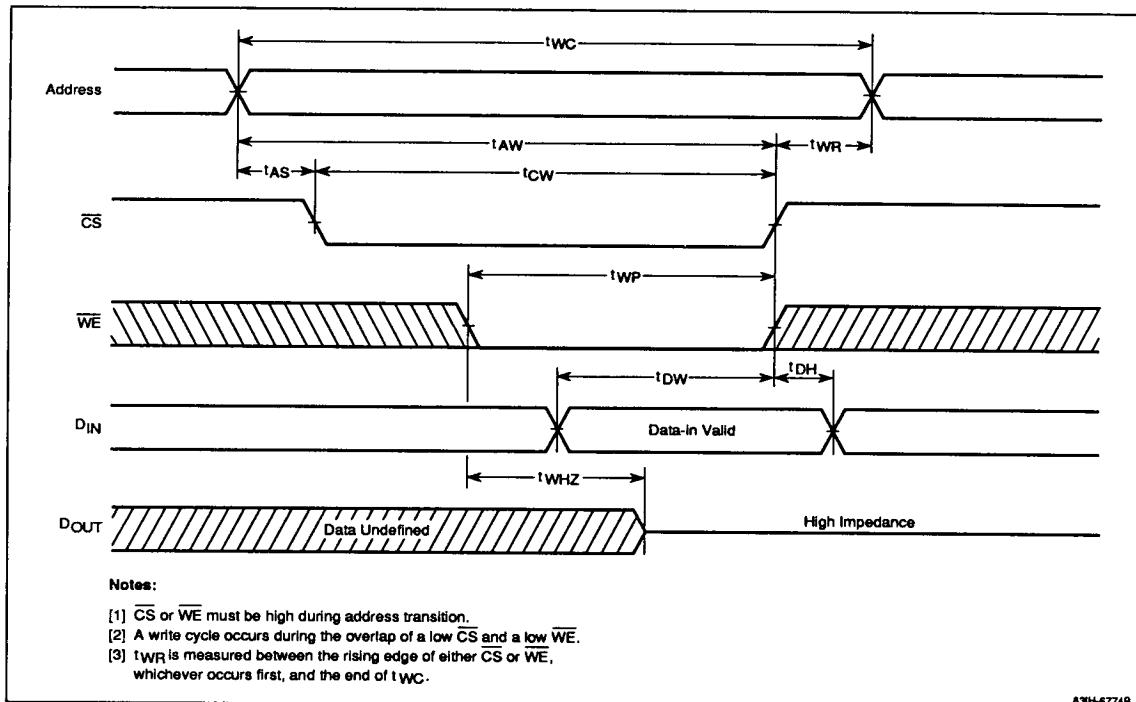
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Timing Waveforms (cont)

WE-Controlled Write Cycle



Timing Waveforms (cont)

 \overline{CS} -Controlled Write Cycle

20e-7